Datasheet revision 1.7

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Heat Sink Compound - High Density 200g Jar

Product Highlights

- High Density Thermal Paste.
- White, non-curing and non-flowing thermally conductive heat sink compound.
- Heavily filled with heat-conductive metal oxide. Provides high thermal conductivity, low bleed and high temperature stability.
- Electrically insulating (2 x 10^{15} ohm-cm).

Specifications

Viscosity:	542,000 cP (542,000 mPa·s)
Density:	2.1g/cc
Bleed:	0.23%
Thermal Conductivity:	0.67 W/m·K
Thermal Resistance:	0.16 °C*cm^2/W
Electrical Volume Resistivity:	2 x 10^{15} ohm-cm
Dielectric Strength:	8.27 MV/m (210V/mil)
Evaporation:	0.38%
Operating Temperature (Continuous):	-40 to 150°C (-40 to 302°F)
Operating Temperature (Peak):	200°C (392°F)
Operating Life:	>8 years *dependent on several factors, test in application to ensure suitability
Size:	200g Jar

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Allow 4 hours for thermal paste to reach an application temperature of 20-25°C (68-77°F) before use.

Shelf Life

>60 months

Stencil Life

>7 days @ 20-70% RH 22-28°C (72-82°F)

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Chip Quik® Thermal Paste Orderable Part Numbers

Thermal Conductivity (W/m·K)	Thermal Resistance (°C*cm^2/W)	Density (g/cc)	Color	Package	Size (g)	Orderable Part Number
0.67	0.16	2.1	White	Syringe	10	TC1-10G
0.67	0.16	2.1	White	Syringe	20	TC1-20G
0.67	0.16	2.1	White	Jar	200	TC1-200G
4.3	0.06	2.5	Grey	Syringe	10	TC2-10G
4.3	0.06	2.5	Grey	Syringe	20	TC2-20G
4.3	0.06	2.5	Grey	Jar	50	TC2-50G
8.5	0.03	2.5	Grey	Syringe	1	TC3-1G
8.5	0.03	2.5	Grey	Syringe	3.5	TC3-3.5G
8.5	0.03	2.5	Grey	Syringe	10	TC3-10G